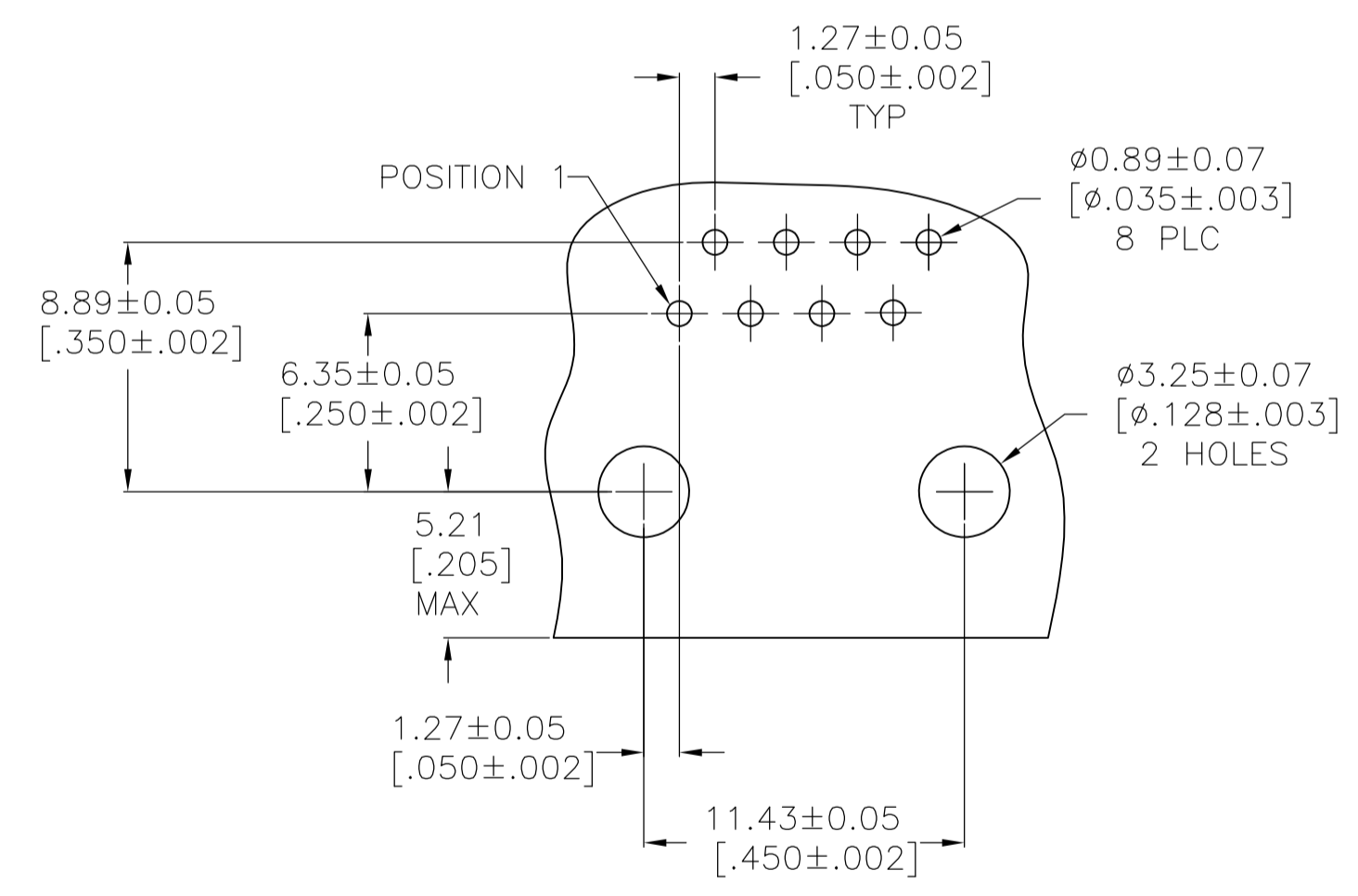
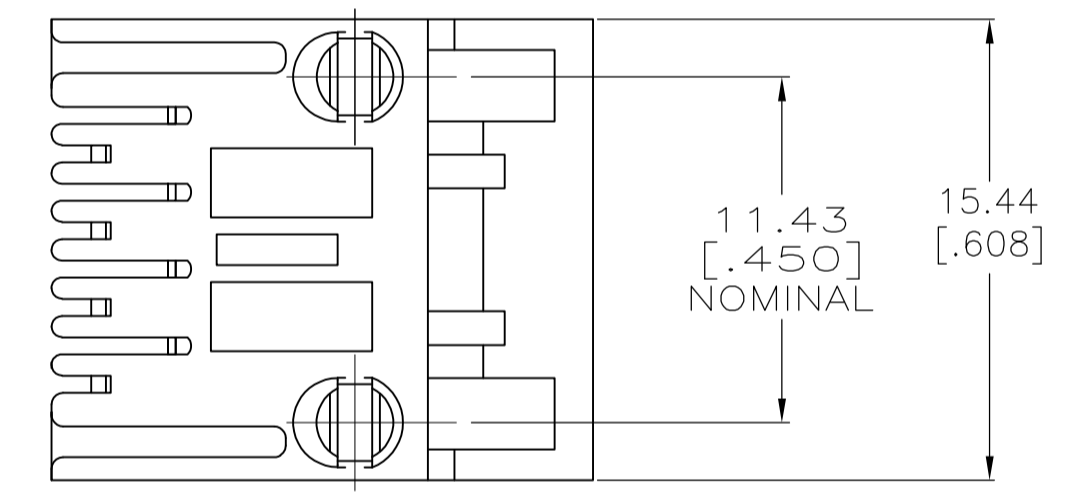
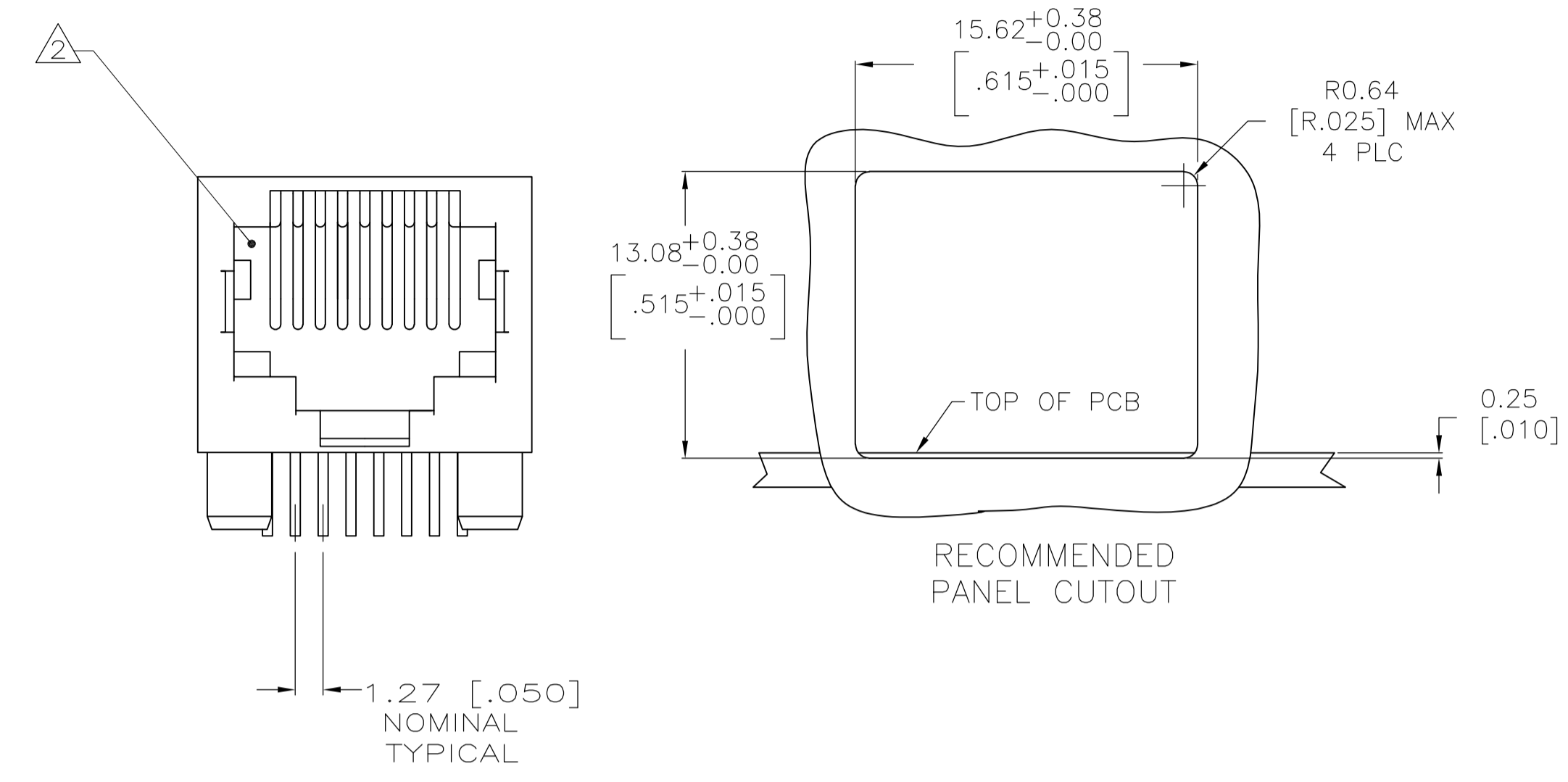
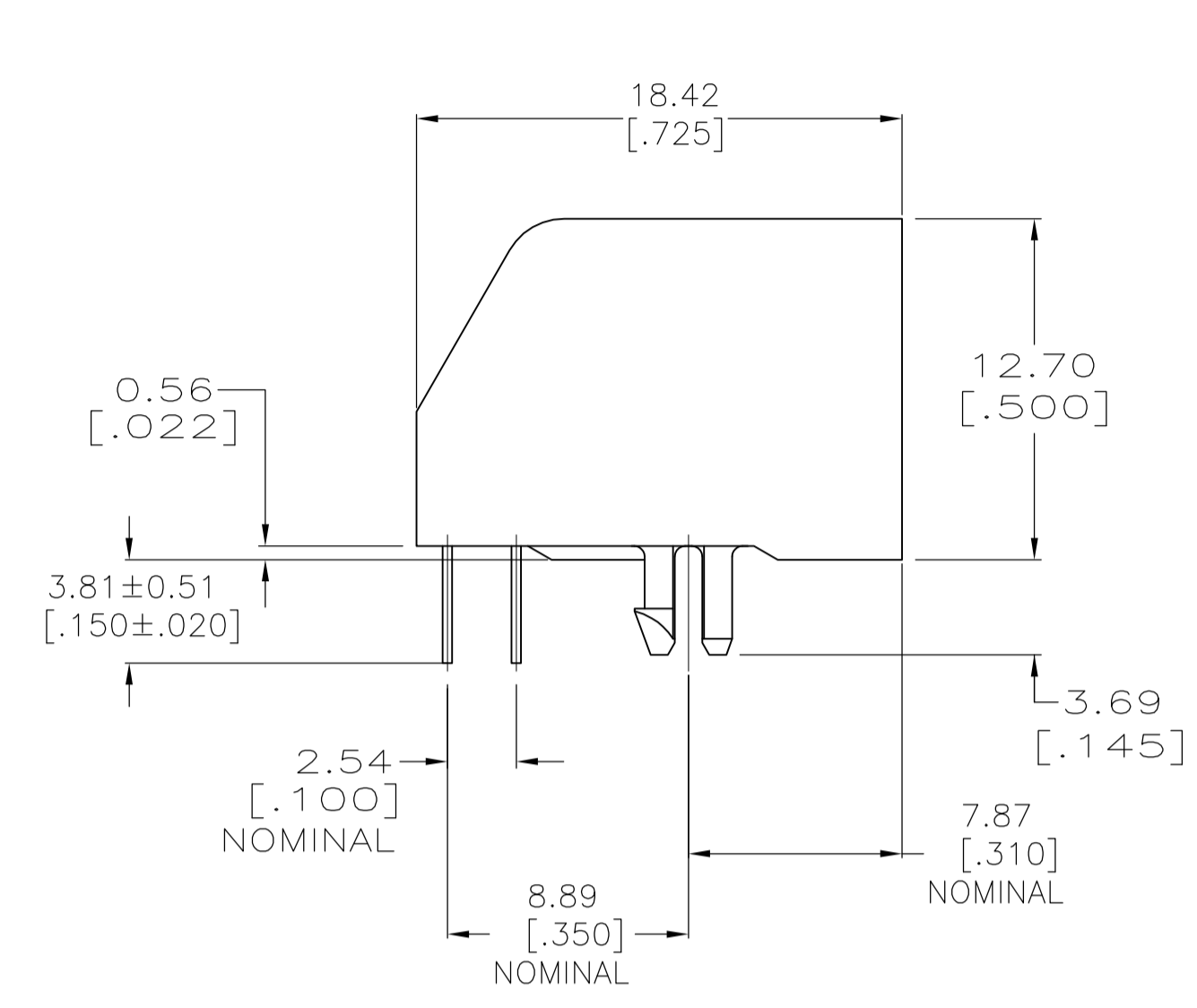


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
B1	REVISED PER ECO-11-005140	28MAR11	RK	HMR			



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

- MATERIAL:  
HOUSING - PBT POLYESTER, COLOR: BLACK  
TERMINAL - 0.36 [0.014] THICK PHOS BRONZE PLATED WITH 1.27µm [0.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [0.000080] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.000050] THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- BULK PACKAGED IN A TRAY.
- 37 ASSEMBLIES PACKAGED PER TUBE

8	5555164-4
8	5555164-1
PACKAGED	TERMINALS REQUIRED PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	0 PLC ± -	1 PLC ± -	2 PLC ± 0.13[0.005]	3 PLC ± -	4 PLC ± -	ANGLES ± -
SEE NOTE 1	SEE NOTE 1	MATERIAL WEIGHT					

DESIGNED BY: G. ATTADIA - DOCKS	DATE: 08/JUN/2005	REVISED BY: J. WESTMAN	DATE: 08/JUN/2005
APPROVED BY: S. FLICKINGER	DATE: 08/JUN/2005	NAME: MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, WITHOUT PANEL STOPS	
PRODUCT SPEC: 108-1163	APPLICATION SPEC: 114-2048	SIZE: A1	SCALE: 4:1
CUSTOMER DRAWING	DRAWING NO: 5555164	SHEET: 1 OF 1	REV: B1

STE TE Connectivity